



Material Content Data Sheet



Sales Product Name		IDH06SG60C		Issued		29. August 2013		
MA#		MA000629796						
Package		PG-TO220-2-1		Weight*		1966.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	siliconcarbide	409-21-2	1.300	0.07		661	
	noble metal	gold	7440-57-5	0.030	0.00		15	
	non noble metal	tin	7440-31-5	0.008	0.00	0.07	4	680
leadframe	non noble metal	iron	7439-89-6	1.343	0.07		683	
	inorganic material	phosphorus	7723-14-0	0.403	0.02		205	
	non noble metal	copper	7440-50-8	1341.263	68.20	68.29	682091	682979
wire	non noble metal	aluminium	7429-90-5	0.692	0.04	0.04	352	352
encapsulation	organic material	carbon black	1333-86-4	9.100	0.46		4628	
	plastics	epoxy resin	-	100.102	5.09		50906	
	inorganic material	silicondioxide	60676-86-0	497.474	25.30	30.85	252987	308521
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7367	7367
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	0	101
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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